PBL 3739
Subscriber Line
Interface Circuit

Description

The PBL 3739 Subscriber Line Interface Circuit (SLIC) is a bipolar integrated circuit in 75V technology, which performs the telephone line interface function.

The programmable battery feed circuit incorporates a switching regulator to minimize on-chip power dissipation and to maintain line feed characteristics independent of battery variations.

Tip-ring polarity is reversible without altering SLIC supervisory and voice frequency (vf) signal functions. In addition, tip and ring outputs can be forced to high-impedance states. These and other operating modes can be set via a parallel four-bit control word.

An external resistor sets the off-hook detector threshold current. The ring trip detector can operate with both balanced and unbalanced ringing systems. A ground key/ ring ground detector examinesthe presence of longitudinal dc current. All detectors are read via a common output.

Ring and test relay drivers are provided.

A stand-by mode minimizes power dissipation while leaving the supervisory functions active.

The two-wire impedance is set by a single lumped-element network.

2-wire to 4-wire and 4- to 2-wire signal conversion is provided by the SLIC in conjunction with either conventional or programmable CODEC/filters.

Longitudinal line voltages are suppressed by a control loop within the SLIC.

The SLIC package is a 44-pin quad cerpac.

Key features

- On-chip switching regulator to minimize power dissipation
- Programmable line-feed resistance
- Line feed characteristics independent of battery variations
- Tip-ring polarity reversal function
- Tip, ring open circuit states
- Programmable off-hook detector
- Ring trip/ring ground detector
- Ring and test relay drivers
- Line terminating impedance (complex or real) set by a simple external network
- Hybrid function with conventional or programmable CODEC/filters
- Longitudinal signal suppression
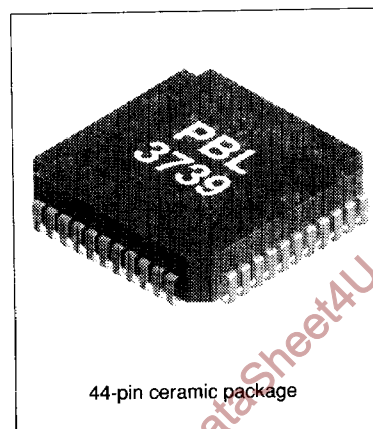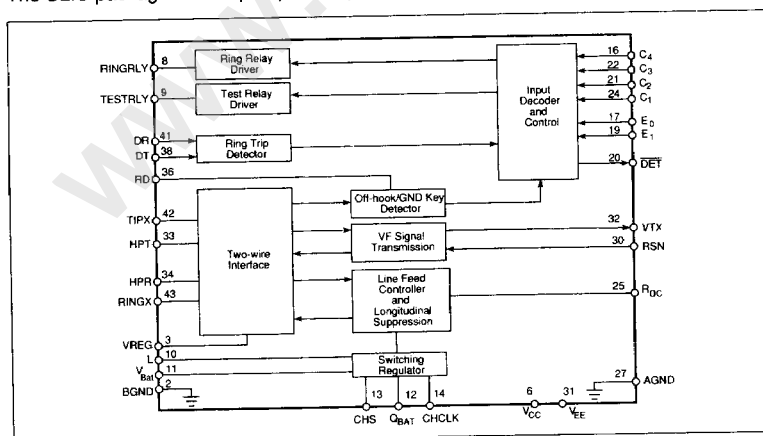
44-pin ceramic package

Maximum Ratings

Parameter	Symbol	Min	Max	Unit
Temperature				
Storage temperature range	T_{Stg}	-55	150	°C
Operating temperature range	T_{Amb}	0	70	°C
Operating junction temperature range, Note 1	T_J		125	°C
Power supply, dissipation				
V_{CC} with respect to AGND	V_{CC}	-0.4	7	V
V_{EE} with respect to AGND	V_{EE}	-7	0.4	V
V_{Bat} with respect to BGND	V_{Bat}	-70	0.4	V
Dissipation at T_{Amb} = 70°C, Note 14			1.5	W
R_L = 50 ohms, R_{Feed} = 2 • 250 ohms				
Ground				
Voltage between AGND and BGND		-0.3	0.3	V
Switching regulator				
Peak current through regulator switch	I_{LPeak}		150	mA
Peak regulator switch-off voltage	V_L		2	V
Relay drivers				
Test relay supply voltage	V_{Test}	V_{Bat}	V_{CC}	V
Ring relay supply voltage	V_{Ring}	V_{Bat}	V_{CC}	V
Test relay current	I_{Test}		50	mA
Ring relay current	I_{Ring}		50	mA
Ring trip comparator				
Input voltage	V_{DT}, V_{DR}	V_{Bat}	0	V
Input current, t_p = 10 ms	I_{DT}, I_{DR}	-2	2	mA
Digital inputs, outputs C_1 — C_4, E_0, E_1, $\overline{DET}$, CHCLK				
Input voltage	V_{ID}	-0.4	V_{CC}	V
Output voltage ($\overline{DET}$ not active)	V_{OD}	-0.3	V_{CC}	V
Output current	I_{OD}		3	mA
TIPX and RINGX terminals				
TIPX or RINGX voltage, continuous referenced to AGND, Note 2	V_{TA}, V_{RA}	V_{Bat}	1	V
TIPX or RINGX, pulse < 10ms, t_{rep} > 10s, Note 2	V_{TA}, V_{RA}	V_{Bat}	5	V
TIPX or RINGX, pulse < 1µs, t_{rep} > 10s, Note 2	V_{TA}, V_{RA}	V_{Bat} -20	10	V
TIP or RING, pulse < 250ns, t_{rep} > 10s, Note 13	V_{TA}, V_{RA}	V_{Bat} -50	15	V
TIPX or RINGX current	I_M	-105	105	mA

Recommended Operating Conditions, Note 3

Parameter	Symbol	Min	Max	Unit
Ambient temperature	T_{Amb}	0	70	°C
V_{CC} with respect to AGND	V_{CC}	4.75	5.25	V
V_{EE} with repect to AGND	V_{EE}	-5.25	-4.75	V
V_{Bat} with respect to BGND	V_{Bat}	-64	-40.5	V
BGND with respect to AGND	V_{AB}	-100	100	mV

Electrical Characteristics

$T_{Amb} = 25°C$, $V_{CC} = +5$ V $\pm 5\%$, $V_{EE} = -5$ V $\pm 5\%$, $V_{Bat} = -40.5$V to -64V, AGND = BGND, 2-wire ac impedance $Z_{TR} = 600$ ohms, $R_{DC1} = R_{DC2} = 20$ kohms, $C_{HP} = 0.22$ μF, $C_{DC} = 0.15$ μF unless otherwise specified

Parameter	Ref. fig.	Conditions	Min	Typ	Max	Unit
Two-wire port						
Overload level, V_{TRO}	1	$Z_L = 600$ ohms, 1% THD $f = 1$kHz, $E_L = 0$, Note 4	3.1			V_{Peak}
Input impedance, Z_{TR}		Note 4, 5				
Longitudinal impedance, R_{LT}, R_{LR}		$f < 100$ Hz		20	40	ohm/wire
Longitudinal current limit, I_{LT}, I_{LR}		active state	28	26		mA_{Peak}/wire
		stand-by state	7	16.8		mA_{Peak}/wire
Longitudinal to metallic balance, B_{LM}		IEEE standard 455-1985 0.2 kHz < f < 3.4 kHz, note 6	48	55		dB
Metallic to longitudinal balance, B_{ML}		FCC part 68, paragraph 68.310				
		0.2 kHz < f < 1.0 kHz	35	48		dB
		1.0 kHz < f < 4.0 kHz, Note 6	35	42		dB
Longitudinal to metallic balance, B_{LME}	2	0.2 kHz < f < 3.4 kHz	48	55		dB
Longitudinal to four-wire balance, B_{LFE}	2	0.2 kHz < f < 3.4 kHz	48	55		dB
Metallic to longitudinal balance, B_{MLE}	2	0.2 kHz < f < 4 kHz	35	42		dB
Four-wire to longitudinal balance, B_{FLE}	2	0.2 kHz < f < 4 kHz	35	42		dB
Two-wire return loss, r		$r = 20 \cdot \text{Log} \dfrac{\lvert Z_{TR} + Z_L \rvert}{\lvert Z_{TR} - Z_L \rvert}$				
		0.2 kHz < f < 0.5 kHz	35	40		dB
		0.5 kHz < f < 1.0 kHz	30	35		dB
		1.0 kHz < f < 3.4 kHz, Note 6	20	28		dB
Polarity reversal time, t_{PR}		Normal to reversed or reversed to normal		15		ms
TIPX idle voltage, V_{TI}		$V_{Bat} = -50$V	-5.5	-4.3	-3.0	V
		$V_{Bat} = -64$V	-5.5	-4.3	-3.0	V
		Normal polarity				
RINGX idle voltage, V_{RI}		$V_{Bat} = -50$V	-42	-40	-38	V
		$V_{Bat} = -64$V	-55	-53	-51	V
		Normal polarity				

Figure 1. Test circuit for transmission parameters.

$\dfrac{1}{\omega C} << R_L$, $R_L = 600$ ohms

$R_T = 600$ kohms, $R_{RX} = 300$ kohms

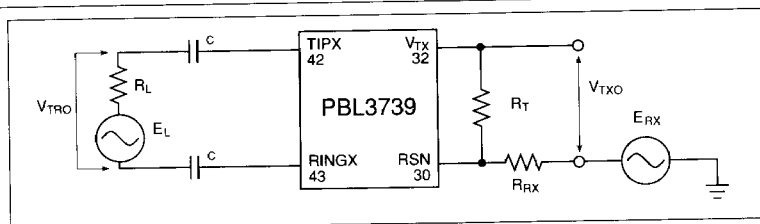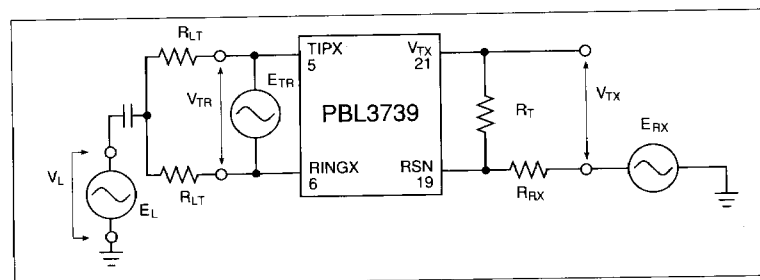*Figure 2. Test circuit for longitudinal balance.*

$\dfrac{1}{wC} << 150$ ohms, $R_{LT} = R_{LR} = 300$ ohms

$R_T = 600$ kohms, $R_{RX} = 300$ kohms

Longitudinal to metallic balance, $B_{LME} =$

$20 \cdot \log \left| \dfrac{E_L}{V_{TR}} \right|$, $E_R = 0$, omit E_{TR}

Parameter	Ref. fig.	Conditions	Min	Typ	Max	Unit
Four-wire transmit port (V_{TX})						
Overload level, V_{TXO}	1	Load impedance > 20 kohms, f = 1kHz, 1% THD, $E_{RX} = 0$, Note 7	3.1			V_{Peak}
Output offset voltage, ΔV_{TX}			-30	± 20	30	mV
Output impedance, z_{TX}		0.2 kHz < f < 3.4 kHz		10	20	ohm
Four-wire receive port (RSN)						
Receive summing node (RSN) dc voltage		$I_{RSN} = 0$	-10	0	10	mV
Receive summing node (RSN) impedance		0.2 kHz < f < 3.4 kHz			20	ohm
Receive summing node (RSN) current (I_{RSN}) to metallic loop current (I_M) gain, G_{RX}		0.2 kHz < f < 3.4 kHz, $R_T = 600$ kohms	980	1000	1020	ratio
Frequency response						
Two-wire to four-wire, g_{2-4}	1	0.3 kHz < f < 3.4 kHz relative to 0 dBm, 1.0 kHz, note 8	-0.1	±0.03	0.1	dB
Four-wire to two-wire, g_{4-2}	1	0.3 kHz < f < 3.4 kHz relative to 0 dBm, 1.0 kHz, note 8	-0.1	±0.03	0.1	dB
Four-wire to four-wire, g_{4-4}	1	0.3 kHz < f < 3.4 kHz relative to 0 dBm, 1.0 kHz, note 8	-0.1	±0.06	0.1	dB
Insertion loss						
Two-wire to four-wire, G_{2-4}	1	0 dBm, 1.0 kHz, Notes 9, 8	-0.15	±0.1	0.15	dB
Four-wire to two-wire, G_{4-2}	1	0 dBm, 1.0 kHz, Notes 9, 10, 8	-0.15	±0.1	0.15	dB
Gain tracking						
Two-wire to four-wire	1	Ref. -10 dBm, 1.0 kHz, Note 8				
		-30 dBm to 3 dBm	-0.1		0.1	dB
		-55 dBm to -30 dBm		±0.1		dB
Four-wire to two-wire	1	Ref. -10 dBm, 1.0 kHz, Note 8				
		3 dBm to -30 dBm	-0.1		0.1	dB
		-30 dBm to -55 dBm		±0.1		dB
Noise						
Idle channel noise	1	C-message weighting		14	16	dBrnC
(two-wire or four-wire)		Psophometrical weighting $R_{Feed} = 2 \cdot 250$ ohms, Note 11		-76	-74	dBmp
Single-frequency out-of-band noise						
Metallic	3	12kHz to 1MHz		-55	-50	dBV
Longitudinal	3	12kHz to 90kH		-68	-63	dBV
		90kHz to 1MHz Note 12		-50	-48	dBV
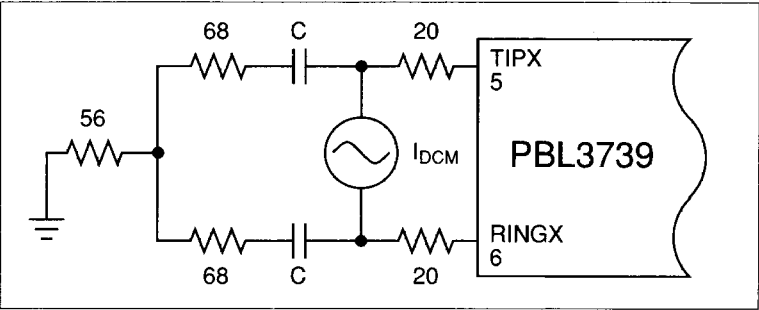
Figure 3. Single frequency noise test circuit.

$\dfrac{1}{\omega C}$ << 100 ohms

Parameter	Ref. fig.	Conditions	Min	Typ	Max	Unit
Total harmonic distortion						
Two-wire to four-wire and		0 dBm, 1.0 kHz test signal		-64	-50	dB
Four-wire to two-wire		$0.3\ kHz < f < 3.4\ kHz$				
Intermodulation						
Type $2 \cdot f_1 - f_2$		$0.3\ kHz < f_1, f_2 < 3.4\ kHz$				
2-wire to 4-wire		Level $f_1 = f_2 = $ -25dBV to 0dBV		-60	-45	dBV
4-wire to 2-wire		$f_1 \neq nf_2, f_2 \neq nf_1$		-60	-45	dBV
Type $f_1 \pm 50Hz$		$0.3\ kHz < f_1 < 3.4\ kHz$				
		Level 50Hz = Level f_1 - 14dB				
		Level f_1 = -15dBV to 0dBV				
2-wire to 4-wire		$f_1 \neq n \cdot 50\ Hz$		-65	-50	-dB
Battery feed characteristics						
Apparent battery voltage			47.5	50	52.5	V
Feed resistance to programming resistance ($R_{DC1} + R_{DC2}$) conversion factor, K_1			47.5	50	52.5	ratio
Stand-by state loop current limit conversion factor, K_{LIM}		$R_L > 50$ ohms, $I_{LIM} = K_{LIM} \cdot I_{DET}$ $I_{DET} = 375/R_D, R_D$ in kohms	$0.8 \cdot I_{DET}$	I_{DET}	$1.2 \cdot I_{DET}$	
Ground key detection threshold						
Resistance, R_{GND}	4	Switch open	1.7		10.0	kohm
interval from ground to RINGX (and TIPX) for ground key detector threshold		Switch closed	0.9		10.0	kohm
Loop current detector threshold (I_{LDET})						
Tolerance with respect to programmed I_{LDET}		Note 12	-20		20	%
Dial pulse distortion				4	10	%
Ring trip detector inputs (D_T, D_R)						
Offset voltage			-20	±10	20	mV
Bias current, I_B		$I_B = (I_{DT} + I_{DR})/2$		0.1	1	µA
Input resistance		Balanced	1			Mohm
		Unbalanced	3			Mohm
Common mode range, V_{TA}, V_{RA}			$V_{Bat} + 1$		-2	V
Relay driver outputs (RINGRLY, TESTRLY)						
On-state voltage		I = 25mA	V_{CC} - 1.8	V_{CC} - 1.3	V_{CC} - 1.0	V
Off-state leakage current		Output voltage = V_{Bat}		5	100	µA
Clamp voltage		I = 25mA	V_{Bat} - 2.0		V_{Bat} - 1.0	V

Figure 4. Ground key detector test circuit.
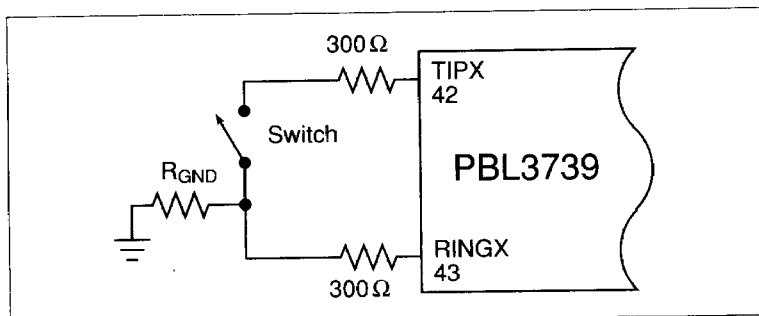
Parameter	Ref. fig.	Conditions	Min	Typ	Max	Unit
Digital Inputs ($C_1 \ldots C_4$, E_0, E_1, CHCLK)						
Input low voltage					0.7	V
Input high voltage			2.0			V
Input low current		$V_{IL} = 0.4V$	-0.4			mA
Input high current		$V_{IH} = 2.4V$			40	µA
Digital Output (DET)						
Output low voltage		$I_{OL} = 1.0mA$			0.45	V
Output high voltage		$I_{OH} = -0.1mA$	2.4			V
Resistive pull-up		Internal resistor	10	15	22	kohm
Switching regulator transistor output (L)						
Saturation voltage, V_{LOSAT}		$I_L = 100mA$			1.5	V
Leakage current, I_{LK}		$V_{LO} = 0V$			200	µA
Switching regulator clock input (CHCLK)						
Clock frequency, f_{CHCLK}			253	256	259	kHz
Power dissipation (relay drivers off)						
V_{CC} supply current		On/off hook, normal mode		7	10	mA
V_{EE} supply current		On/off hook, normal mode		2	3	mA
V_{Bat} supply current		On hook, normal mode		4	6	mA
On-hook total dissipation		$V_{Bat} = -60$ V, open circuit mode		50	90	mW
		$V_{Bat} = -60$ V, stand-by mode		200	350	mW
		$V_{Bat} = -60$ V, normal mode		325	400	mW
Off-hook total dissipation		$V_{Bat} = -60$ V, normal mode		800	1000	mW
		$R_L = 600$ ohms,				
		$R_{DC1} + R_{DC2} = 40$ kohms				
Thermal resistance						
Junction to ambient, Θ_{JA}		44-pin ceramic j-leaded chip carrier		33		°C/W

Notes

1. The circuit includes thermal protection. Operation at or above 125°C junction temperature may degrade device reliability.

2. A diode in series with the V_{Bat} input increases the permitted continuous voltage and pulse < 10ms to -70V and pulse < 1µs to the greater of |-70V| or |V_{Bat} - 40V|.

3. BGND and AGND must be connected before supply voltages. Application of V_{Bat} with a low rate of change is recommended. Refer to section "Power-up sequence".

4. The overload level is specified at the two-wire port with the signal source at the four-wire port.

5. The two-wire impedance is programmable by selection of external component values according to:

   Z_{TRX} = $Z_T/|G_{TX} \cdot G_{RX}|$ where:

   Z_{TRX} = impedance between the TIPX and RINGX terminals

   Z_T = programming network between the V_{TX} and RSN terminals

   G_{TX} = transmit gain, nominally = 1

   G_{RX} = receive current gain, nominally = -1000 (current defined as positive flowing into the receive summing node, RSN pin 19).

6. The indicated balance and two-wire return loss values do not include errors caused by external components (e.g. R_{F1}, R_{F2}, R_T).

7. The overload level is specified at the four-wire transmit port, V_{TX}, with the signal source at the two-wire port. Note that the gain from the two-wire port to the four-wire transmit port is $G_{TX} = 1$.

8. The level is specified in dBm, 600 ohms impedance level.

9. Fuse resistors, R_F, impact insertion loss as explained in the text, section Transmission.

10. The indicated insertion loss tolerance does not include errors caused by external components.

11. The two-wire idle noise is specified with the port terminated in 600 ohms (R_L) and with the four-wire receive port grounded (E_{RX} = 0). The four-wire idle noise at V_{TX} is specified with the two-wire port terminated in 600 ohms (R_L). The noise specification is with respect to a 600 ohms impedance level at V_{TX}. The four-wire receive port is grounded (E_{RX} = 0).

12. These specifications are valid for a longitudinal impedance of 90 ohms and a metallic impedance of 135 ohms.

13. R_{F1}, $R_{F2} \geq 20$ ohms is also required. Pulse is supplied to TIP and RING outside R_{F1}, R_{F2}.

14. Value applies for momentarely junction temperature of 120 °C for 44-pin LCC without heatsink.

Pin Descriptions

Refer to figure 5 (44-pin ceramic leaded chip carrier package, LCC).

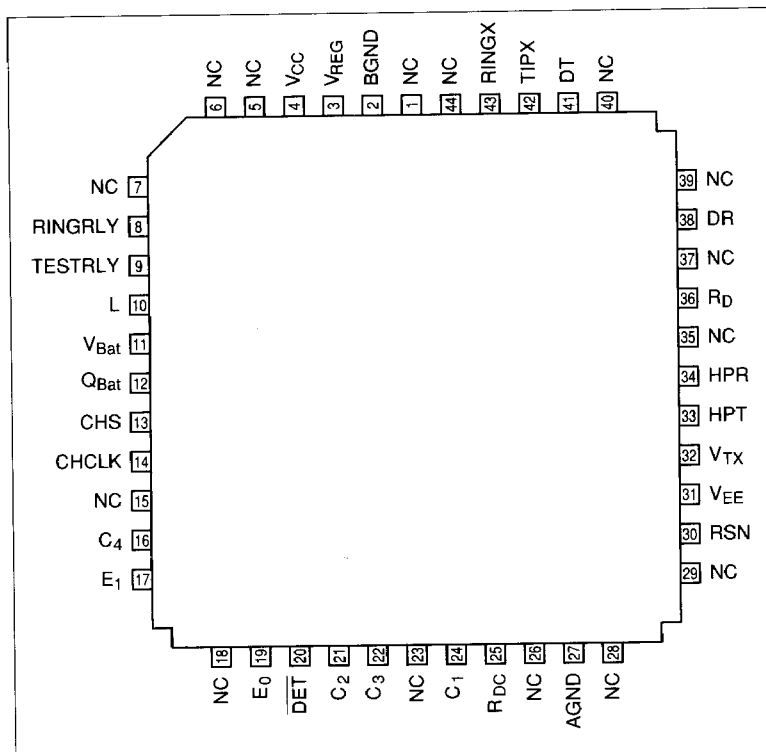| Pin	Symbol	Description
1	N/C	No internal connection. Note 1.
2	BGND	Battery ground.
3	V_{REG}	Regulated negative voltage for power amplifiers. The switching regulator inductor, filter capacitor, and RC stabilization network connect to this pin.
4	V_{CC}	+5V power supply.
5	N/C	No internal connection. Note 1.
6	N/C	No internal connection. Note 1.
7	N/C	No internal connection. Note 1.
8	RINGRLY	Ring relay driver output. Sources 25mA from V_{CC}.
9	TESTRLY	Test relay driver output. Sources 25mA from V_{CC}.
10	L	Switching regulator drive transistor output. The 1 mH inductor and the catch diode connect to this pin. These components must be connected with shortest possible lead lengths. The catch diode, including connecting leads, must exhibit a low inductance to effectively clamp when the regulator switch opens.
11	V_{Bat}	Battery supply voltage. Negative with respect to BGND, pin 1.
12	Q_{Bat}	Quiet battery. An external filter capacitor connects between this pin and AGND to provide filtered battery supply to signal processing circuits.
13	CHS	Switching regulator stabilization network input. From this pin, a capacitor connects to AGND and a series RC network to V_{REG}, pin 2.

Figure 5. Pin configuration.

14	CHCLK	Switching regulator TTL-compatible clock input. Nominal frequency: 256 kHz.
15	N/C	No internal connection. Note 1.
16	C_4	C_1 (pin 16), C_2 (pin 14), C_3 (pin 15), and C_4 are TTL-compatible decoder inputs controlling the SLIC operating modes and states.
17	E_1	Detector select. E_1 = high enables Ground Key detector. E_1 = low enables the Loop/Ring-trip detector. TTL-compatible input.
18	N/C	No internal connection. Note 1.
19	E_0	Read enable. A logic high enables $\overline{DET}$ (pin 13). A logic low disables $\overline{DET}$. TTL-compatible input.
20	$\overline{DET}$	Detector output. Inputs $C_1 \ldots C_4$ select the detector to be connected to this output. When $\overline{DET}$ is enabled via E_0 (pin 12), a logic low indicates that the selected detector is to be tripped. The $\overline{DET}$ output is open collector with internal pull-up resistor (approx, 15 Kohm) to V_{CC} (pin 3). When disabled, $\overline{DET}$ thus appears to be a resistor connected to V_{CC}.
21	C_2	Refer to pin 16.
22	C_3	Refer to pin 16 .
23	N/C	No internal connection. Note 1.
24	C_1	Refer to pin 16.
25	R_{DC}	DC feed resistance is programmed by two resistors connected in series from this pin to the receive summing node (RSN, pin 30). The resistor junction point is decoupled to AGND to filter noise and disturbances before reaching the RSN pin. V_{RDC} polarity is negative for normal tip-ring polarity and positive for reversed tip-ring polarity. $$\mid V_{RDC} \mid = \mid (\mid V_{HPT} - V_{HPR} \mid - 50V) / 20 \mid$$
26	N/C	No internal connection. Note 1.
27	AGND	Analog and digital ground. Analog ground is a quiet ground for vf signal processing circuits.
28	N/C	No internal connection. Note 1.
29	N/C	No internal connection. Note 1.
30	RSN	Receive summing node. 1000 times the current (dc and ac) flowing into this pin equals the metallic (transversal) current flowing between TIPX (pin 42) and RINGX (pin 43). Programming networks for feed resistance, 2-wire impedance, and receive gain connect to the receive summing node.
31	V_{EE}	-5V power supply.
32	V_{TX}	Transmit vf output. The ac voltage difference between TIPX (pin 42) and RINGX (pin 43), the ac metallic voltage, is reproduced as an unbalanced AGND-referenced signal at V_{TX} with a gain of one. The two-wire impedance programming network connects between V_{TX} and RSN (pin 30).
33	HPT	Ring side (HPR) and tip side (HPT) of ac/dc separation capacitor.
34	HPR	
35	N/C	No internal connection. Note 1.
36	R_D	Off-hook detector programming resistor connects from R_D to V_{EE} (pin 31). A filter capacitor, C_D, connects from R_D to AGND. In the stand-by mode, the maximum loop current is 1.5 times the threshold current set by R_D.
37	N/C	No internal connection. Note 1.
38	DR	Non-inverting input to ring trip comparator.
39	N/C	No internal connection. Note 1.
40	N/C	No internal connection. Note 1.
41	DT	Inverting (DT) input to ring trip comparator.
42	TIPX	The TIPX and RINGX pins connect to the tip and ring leads of the 2-wire line interface via over-voltage-protection
43	RINGX	components, ring and test relays.
44	N/C	No internal connection. Note 1.

Note 1. Pins marked N/C are not internally connected. It is recommended to connect these pins to ground.

Transmission

General

A simplified ac model of the transmission circuits is shown in figure 7 Circuit analysis yields:

$$V_{TR} = V_{TX} + I_M \cdot 2R_F \quad (1)$$

$$\frac{V_{TX}}{Z_T} + \frac{V_{RX}}{Z_{RX}} = \frac{I_M}{1000} \quad (2)$$

$$V_{TR} = E_G - I_M \cdot Z_L \quad (3)$$

where:

V_{TX} is a ground referenced unity gain version of the ac metallic voltage between the TIPX and RINGX terminals.

V_{TR} is the ac metallic voltage between tip and ring.

E_G is the line open circuit ac metallic voltage.

I_M is the ac metallic current.

R_F is a fuse resistor.

Z_L is the line impedance.

Z_T determines the SLIC TIPX to RINGX impedance.

Z_{RX} controls four- to two-wire gain.

V_{RX} is the analog ground referenced receive signal.

The low pass filter, block A, shown in figure 7 will impact the 2-wire to 4-wire, 4-wire to 2-wire and 4-wire to 4-wire phase response in the voice frequency band. At 3.4 kHz the phase shift is 3 to 5 degrees. Contact the factory for additional information. Note that equations (1), (2) and (3) above do not acount for this phase shift.

Two-wire impedance

To calculate Z_{TR}, the impedance presented to the two-wire line by the SLIC including the fuse resistors R_F, let:

$V_{RX} = 0$. Then, from (1) and (2):

$$Z_{TR} = Z_T/1000 + 2R_F$$

Thus with Z_{TR} and R_F known:

$$Z_T = 1000 \cdot (Z_{TR} - 2R_F)$$

Example:
Calculate Z_T to make $Z_{TR} = 900\Omega$ in series with 2.16 µF. $R_F = 20 \ \Omega$

$$Z_T = 1000 \cdot (900 + \frac{1}{j \cdot \omega \cdot 2.16 \cdot 10^{-6}} - 2 \cdot 20)$$

which yields:

$Z_T = 860$ kΩ in series with 2.16 nF.

Two-wire to four-wire gain

From (1) and (2) with $V_{RX} = 0$:

$$G_{2-4} = \frac{V_{TR}}{V_{TR}} = \frac{Z_T/1000}{Z_T/1000 + 2R_F}$$

For applications where $Z_T/1000 + 2R_F$ is chosen to be equal to Z_L the expression for G_{4-2} simplifies to $G_{4-2} = -\frac{Z_T}{Z_{RXB}} \cdot \frac{1}{2}$.

Four-wire to two-wire gain

From (1), (2) and (3) with $E_G = 0$:

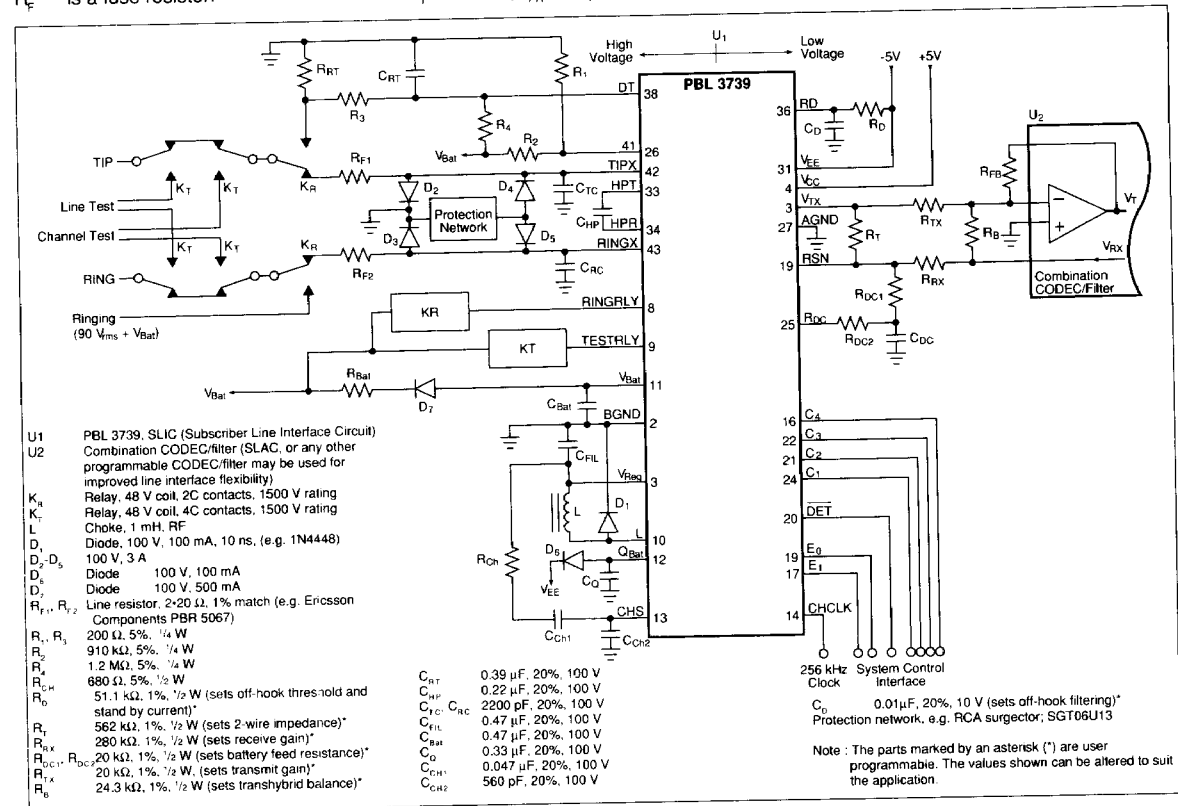$$G_{4-2} = \frac{V_{TR}}{V_{RX}} = -\frac{Z_T}{Z_{RX}} \cdot \frac{Z_L}{Z_T/1000 + 2R_F + Z_L}$$

Figure 6. Single-channel subscriber line interface with PBL 3739 SLIC and a combination CODEC/filter.

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Four-wire to four-wire gain

From (1), (2) and (3) with $E_G = 0$:

$$G_{4-4} = \frac{V_{TX}}{V_{RX}} = -\frac{Z_T}{Z_{RX}} \cdot \frac{Z_L + 2 \cdot R_F}{Z_T/1000 + 2 \cdot R_F + Z_L}$$

Hybrid function

The PBL 3739 SLIC forms a particularly flexible and compact line interface when used with a SLAC (Subscriber Line Audio Processing Circuit) or other programmble CODEC/filter. The SLAC allows for system controller adjustment of hybrid balance to accommodate different line impedances without change of hardware. In addition, the SLAC permits transmit and receive gain adjustments in 0.1 dB steps. Please, refer to SLAC or other programmableCODEC/filter data sheets for design information.

The hybrid function can also be implemented utilizing the uncommitted amplifier in conventional CODEC/filter combinations. Please, refer to figure 8. Via impedance Z_B a current proportional to V_{RX} is injected into the summing node

of the combination CODEC/filter amplifier. As can be seen from the expression for the four-wire to four-wire gain a voltage proportional to V_{RX} is returned to V_{TX}. This voltage is converted by R_{TX} to a current into the same summing node. These currents can be made to cancel by letting:

$$\frac{V_{TX}}{R_{TX}} + \frac{V_{RX}}{Z_B} = 0, (E_G = 0)$$

The four-wire to four-wire gain, G_{4-4}, includes the required phase shift and thus the balance network Z_B can be calculated from:

$$Z_B = -R_{TX} \cdot \frac{V_{RX}}{V_{TX}}$$

$$= R_{TX} \cdot \frac{Z_{RX}}{Z_T} \cdot \frac{Z_T/1000 + 2 \cdot R_F + Z_L}{Z_L + 2 \cdot R_F}$$

Longitudinal impedance

A feedback loop counteracts longitudinal currents in opposing phase. Thus longitudinal disturbances will appear as longitudinal currents and the TIPX and RINGX terminals will experience very small longitudinal votage excursions, leaving the metallic voltages well within the SLIC common mode range. This is accomplished by comparing the instantaneous two-wire longitudinal voltage to an internal longitudinal reference voltage, V_{LBIAS}. As shown below the SLIC appears as 20 ohms per wire to longitudinal disturbances. It should be noted that longitudinal currents may exceed the dc loop current without disturbing the vf transmission. Refer to figure 9. Circuit analysis yields

$(V_L/2 + V_L/2)/20$ kohms$= I_L/1000$

which reduces to $R_{LT} = R_{LR} = V_L/I_L = 20$ ohms where:

$R_{LT} = R_{LR}$ = longitudinal resistance/wire

V_L = longitudinal voltage at TIPX, RINGX

I_L = longitudinal current

Ac transmission circuit stability

To ensure stability of the feedback loop shown in block diagram form in figure 7, two compensation capacitors C_{TC} and C_{RC} are required. Figure 6 includes these capacitors. Recommended value is 2200 pF.

Battery Feed

Line feed characteristics

Figure 10 shows the battery feed control loop. Circuit analysis for the normal polarity case yields:

$$I_{DCMET} = \frac{|V_{DCMET}| - 50V}{(R_{DC1} + R_{DC2})/50}$$

where V_{DCMET} is the dc metallic voltage between TIPX and RINGX terminals and I_{DCMET} is the dc loop current. The loop thus has an apparent feed voltage of 50V with a feed resistance

$$R_{Feed} = (R_{DC1} + R_{DC2})/50$$

The polarity-reversal transition time is dependent on the time constant formed by R_{DC1}, R_{DC2} and C_{DC}. This time constant should be set to between 0.4 and 1.0 ms. $R_{DC1} = R_{DC2}$ results in the smallest C_{DC} value.

A: Lowpass filter, -3 dB @ ≈ 34 kHz
B: Highpass filter, -3 dB @ ≈ 1.8 Hz
C: Lowpass filter, -3 dB @ ≈ 1.8 Hz
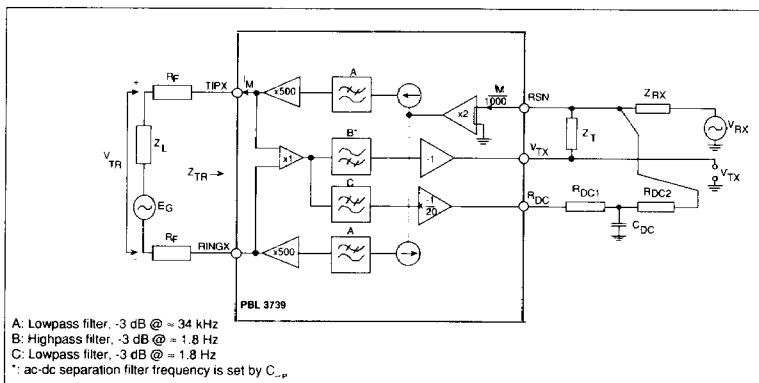*: ac-dc separation filter frequency is set by C_LP
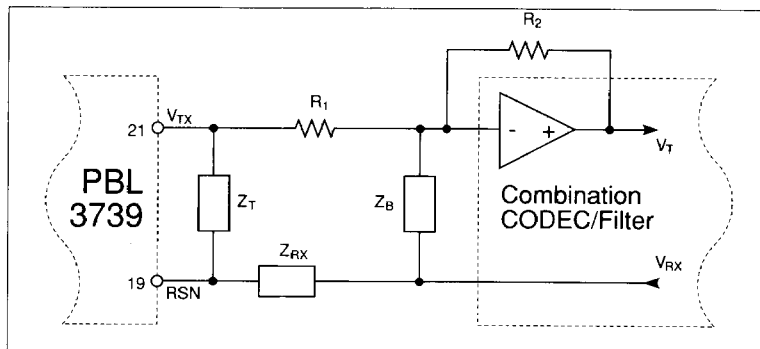
Figure 7. Simplified ac transmission circuit.

Figure 8. Hybrid function.

The PBL 3739 dc feed-programming components may then calculated from

$$R_{DC1} = R_{DC2} = \frac{1}{2} \cdot 50 \cdot (R_{FEED} - 2R_F)$$

$$C_{DC} = T \cdot (R_{DC1} + R_{DC2}) / (R_{DC1} \cdot R_{DC2})$$

where R_{FEED} is the SLIC desired feed resistance. R_F is the value of the two fuse resistors, normally 20 ohms each. T is between 0.4 and 1.0 ms.

The switching regulator supplies a voltage to the line drivers of:

$$|V_{REG}| = |V_{DCMET}| + V_{BIAS}$$

where V_{BIAS} is approximately 15V.

It is necessary for $|V_{REG}| < |V_{Bat}|$ to maintain a resistive feed characteristic. Especially for short loops $|V_{REG}|$ is considerably smaller than $|V_{Bat}|$. Since the switching regulator efficiency is high, a substantial power dissipation reduction is thus achieved compared with to a design $|V_{Bat}|$ supplied directly to the line drive amplifiers. With $V_{Bat} = -50V$, the maximum $|V_{DCMET}| = 50V - 15V = 35V$. To feed the loop with at least 18 mA, a maximum loop resistance of 35V/18mA = 1940 ohms can then be achieved with $V_{Bat} = -50V$. The feed resistance to design for would be 15V/18mA = 830 ohms. Longer loops are accommodated by selecting a higher V_{Bat} voltage, while not exceeding the maximum allowable V_{Bat} voltage.

Switching regulator

Refer to figure 11. The regulator input voltage is V_{Bat} (pin 11). This voltage is converted with high efficiency to V_{REG} (pin 3) which supplies the line drivers. The regulator reference voltage, V_{REF}, is derived from the TIPX-to-RINGX dc metallic voltage according to:

$$V_{REG} = V_{REF} = |V_{DCMET}| + V_{BIAS}$$

where V_{BIAS} is approximately 15V. Thus the voltage supplying the line driver is never more than is necessary and consequently the power dissipation in the SLIC is therefore substantially reduced.

The components associated with the switching regulator must be connected via shortest possible trace lenghts. Other circuits should be kept isolated from this area. The L pin (10) voltage variations are large and very fast. The catch diode (e.g. 1N4448) should withstand 70V reverse voltage, conduct an average of 50mA (150mA peak) and turn off in less than 10ns. The inductor should be 1mH with a series resistance of approximately 10

ohms and a capacitance of less than10 pF. The inductor must withstand peak currents of 150 mA without saturating. Iron-core is suggested to avoid inductor saturation. J. W. Miller 9220-28 or Nytronics RFC-S are possible choices. Ferrite-pot core inductors may also be used. Note, however, that a saturated, low-loss inductor may result in SLIC damage due to excessive regulator switching current. Closed magnetic path inductor cores (e.g. toroid, pot core) are less prone to generate interfering magnetic fields than inductors wound on open cores and may thus reduce possible 256 kHz interference.

Loop Monitoring Functions

The PBL 3739 includes three loop-monitoring functions: loop current, ground

key and ring trip detection. These three detectors report their status through a common output, $\overline{DET}$ (pin 20). The detector to be connected to $\overline{DET}$ is selected via decoder inputs C_1 through C_3 and enable E_1. The $\overline{DET}$ output is enabled via the read-enable input E_0 (pin 19).

Loop current detector

The loop current value, at which the loop current detector changes state, is programmable by selecting the value of resistor R_D. R_D connects between pins RD (36) and V_{EE} (31). A filter capacitor, C_D, should be connected between R_D (36) and AGND. Note that C_D may not be required if the $\overline{DET}$ output is software filtered.

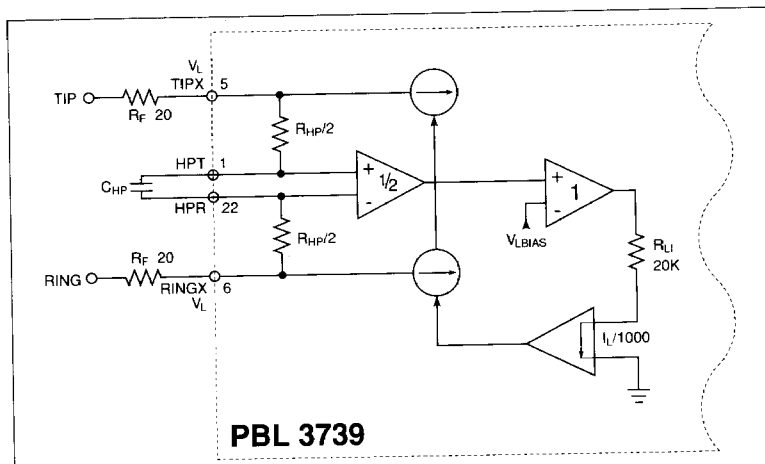Figure 12 shows a block diagram of the loop current detector. The two-wire
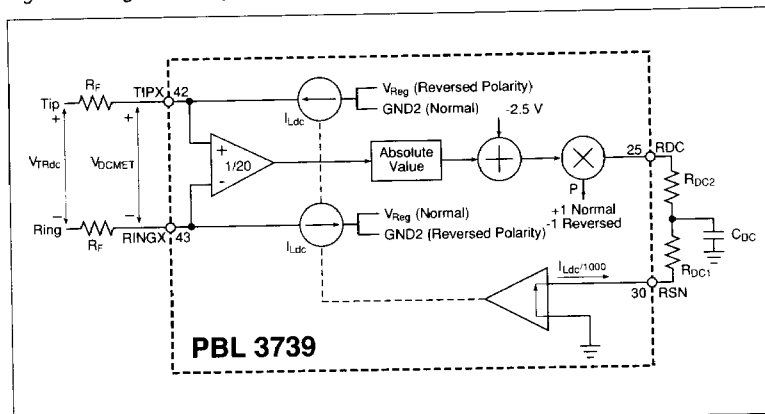

Figure 9. Longitudinal impedance.

Figure 10. Battery feed.

interface produces a current flowing out of pin RD (36):

$I_{RD} = |I_{TIP} - I_{RING}|/(2 \cdot 300) = I_L/300$

where I_{TIP} and I_{RING} are currents flowing into the TIPX and RINGX terminals and I_L is the loop current. The voltage generated by I_{RD} across the programming resistor R_D is compared to an internal 1.25 V reference. A logic low results at $\overline{DET}$, when I_{RD} exceeds the corresponding threshold current,

$I_{RD} = I_{THRESH} = I_{LTH}/300$. The programming resistor can then be calculated as $R_D = 1.25/I_{THRESH} = 375/I_{LTH}$, when the desired threshold current I_{LTH} is known. R_D is in kohms for I_{THRESH}, I_{LTH} in mA. The filter capacitor is calculated according to $C_D = T/R_D$ with time constant $T = 0.25$ ms.

Ground key detector

The block diagram in figure 12 describes the function of the ground key detection.

The ground key detector examines the longitudinal part of the TIPX and RINGX currents or the currents into the most-negative terminal (commonly known as RINGX) itself.

When the longitudinal current from ground exceeds a threshold value, 7 mA, the detector is triggered. Provided the E_1 input is set to a logic high, the $\overline{DET}$ output changes to low.

The ground key/ ring ground threshold is pre-programmed and cannot be changed by external components.

Ring trip detector

Ring trip detection is accomplished by connecting an external network to a comparator in the SLIC with inputs DT (pin 38) and DR (pin 41). The ringing source can be balanced or unbalanced superimposed on V_{Bat}. The unbalanced ringing source may be applied to either the ring lead or the tip lead with return to the other wire. A ring relay driven by the SLIC ring relay driver connects the ringing source to tip and ring.

Figure 13 shows a balanced ringing circuit configuration. R_1 and R_2 are the ring feed resistors, which connect the balanced ringing generator E_{R+} and E_{R-} to the telephone line via ring relay K_R. R_{B1}, R_{B2}, R_3, and R_4 together with the SLIC comparator provide the ring trip detection function. For unbalanced ringing, E_{R+} would be zero.

The ring trip function is based on a polarity change at the comparator input when the line goes off-hook. In the on-hook state no dc current flows through the loop and the voltage at comparator input DT is more positive than the voltage at input DR. When the line goes off-hook, dc current flows and the comparator input voltage reverses polarity.

The capacitors, C_{RT1} and C_{RT2}, reduce the ringing voltage amplitude at the comparator inputs, DT and DR, to be within the maximum allowable voltage range. They also reduce comparator oscillation at the ringing frequency near the threshold. In the balanced ringing case, C_{RT1} and C_{RT2} can be combined into one capacitor of half-value, connected between the D_T and D_R terminals. For 20Hz ringing, it is suitable to calculate the capacitor(s) for a 50ms time constant (e.g., $T_1 = C_{RT1} \cdot R_{B1} \cdot R_3 / (R_{B1} + R_3)$).
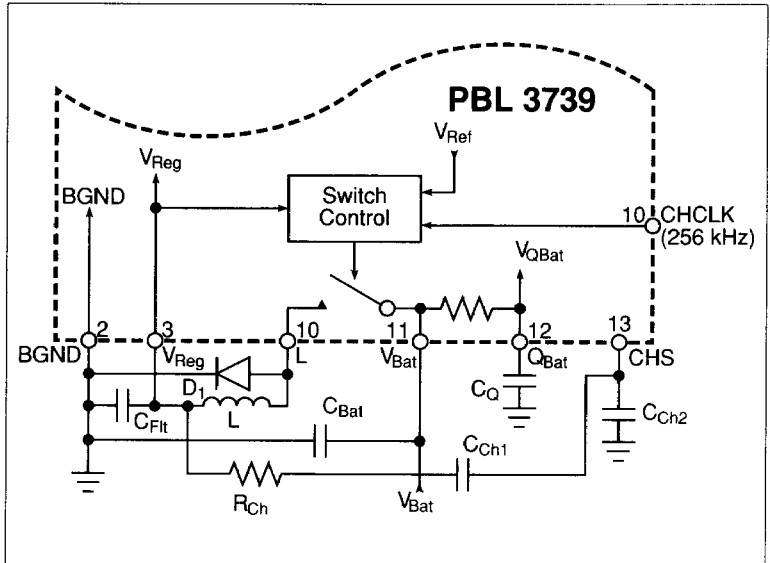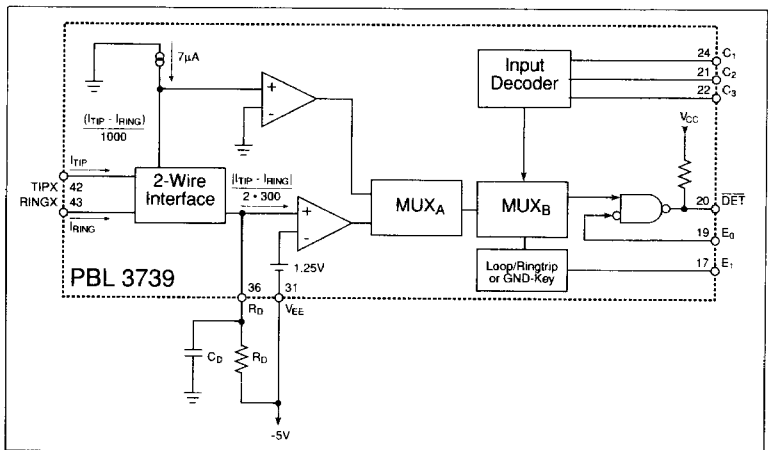

Figure 11. Switching regulator.

Figure 12. Loop current and ground key detector.

For balanced ringing, $R_3 = R_4$. Select $R_{B1} = R_{B2} = R_3 (R_1 + R_2 + R_{LINE}) / R_{LINE}$ where R_{LINE} is the maximum line resistance to be detected as off-hook.

Detector output

The loop current detector ground key detector and the ring trip comparator share a common output, $\overline{DET}$ (pin 20). Via control inputs C_1 through C_3 and enable input E_1, one of the three is selected to be connected to $\overline{DET}$. When input E_0 is set to logic high, the $\overline{DET}$ output is logic low for tripped detector condition and logic high for non-tripped condition. The $\overline{DET}$ output is open collector with built-in pull-up resistor. When E_0 is set to logic low, the $\overline{DET}$ output is disabled, i.e., connected to V_{CC} via the internal pull-up resistor.

Control Inputs

The PBL 3739 SLIC has four TTL-compatible control inputs, C_1 through C_4. A decoder in the SLIC interprets the control input conditions and sets up the commanded operating state. C_1 through C_3 allow for eight operating states. The C_4 logic level determines whether the test relay is energized or not during the selected operating state. The control inputs interface directly with programmable CODEC/filter devices (e.g. SLAC, Subscriber Line Audio Processing Circuit). Via serial I/O ports on the SLAC, a micro-processor can communicate with all the SLIC-SLAC pairs on a line card. Refer to programmable CODEC/filter device literature for details.

Test relay control (C_4)

With C_4 set to logic level low, the test relay driver (TESTRLY) is activated (sourcing up to 25mA from V_{CC}) and with C_4 set to logic level high, the test relay driver is switched off. The test relay driver control input C_4 is independent of C_1, C_2 and C_3 logic levels.

Open circuit state (C_3, C_2, $C_1 = 0, 0, 0$)

In the open circuit state, both the TIPX and RINGX power amplifiers present a high-impedance to the line. The loop current or ground key detector is not active in this state.

Ringing state (C_3, C_2, $C_1 = 0, 0, 1$)

The ring relay driver (RINGRLY) is activated and the ring trip detector is connected to the detector output ($\overline{DET}$). TIPX and RINGX are in the high-impedance state and signal transmission is inhibited.

Normal state (C_3, C_2, $C_1 = 0, 1, 0$)

TIPX is the terminal closest to ground and sources loop current, while RINGX is the more-negative terminal and sinks loop current. Signal transmission is normal and the loop current or ground key detector is gated to the $\overline{DET}$ output.

Stand-by state (C_3, C_2, $C_1 = 0, 1, 1$)

The loop current is limited to 1.5 times the loop current detector threshold current. The TIPX and RINGX power amplifiers can still handle 20mA (10mA/wire) longitudinal currents. The loop current or ground key detector is connected to the $\overline{DET}$ output.

TIPX open circuit state (C_3, C_2, $C_1 = 1, 0, 0$)

The TIPX power amplifier presents a high-impedance to the line, while RINGX sinks a maximum of 35mA to V_{BAT}. The loop current detector is connected to the $\overline{DET}$ output, but in this state tripping at a RINGX current equal to $750/R_D$.

Reserved state (C_3, C_2, $C_1 = 1, 0, 1$)

This state is reserved (no function assigned).

Polarity reversal state (C_3, C_2, $C_1 = 1, 1, 0$)

TIPX and RINGX polarity is reversed from the normal state; RINGX is closest to ground and sources current, while TIPX is the more-negative terminal and sinks current. Transition time from normal state is approximately 15ms. The loop current or ground key detector is connected to the DET output. Signal transmission is normal.

Polarity reversal and stand-by state (C_3, C_2, $C_1 = 1, 1, 1$)

Polarity reversal as described under state C_3, C_2, $C_1 = 1, 1, 0$ and disabled as described under state C_3, C_2, $C_1 = 0, 1, 1$.

Overvoltage Protection

The PBL 3739 SLIC must be protected against overvoltages and power crosses. Refer to "Maximum ratings" for TIPX and RINGX terminals for maximum allowable transient voltages that may be applied to the SLIC. The circuit shown in figure 6 utilizes diodes together with a clamping device to protect against high voltage transients. Diodes D_2 and D_3 clamp positive transients directly to ground. These two diodes are reverse biased by the normal, negative tip and ring operating voltages Diodes D_4 and D_5 clamp negative transients to ground via a device, which is not conducting when exposed to the normal, negative tip and ring operating voltages, but will conduct
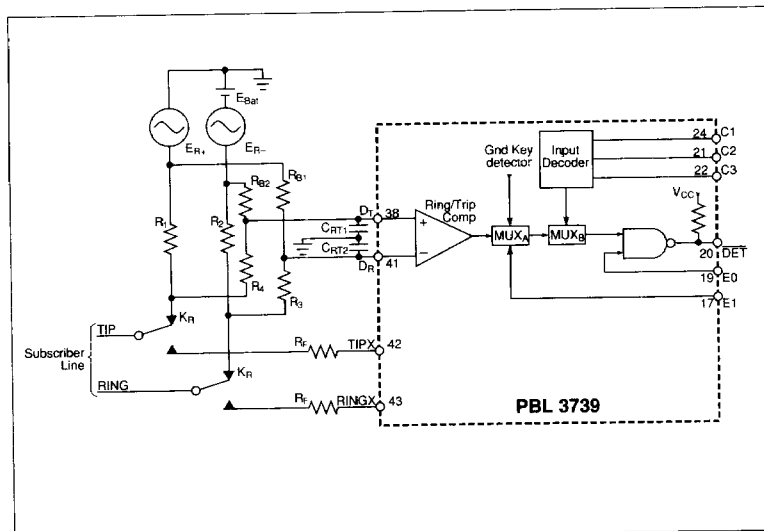

Figure 13. Ring trip detector.

when exposed to negative transient voltages. This device is necessary since D_4 and D_5 would otherwise be forward biased in the normal operating mode. A zener diode type device (e.g. General Semiconductor Transzorb) is suitable for lower energy transients and an SCR type device (e.g. RCA Surgector) is suitable for higher energy transients due to its voltage foldback characteristic. In applications requiring protection only against low energy transients it is acceptable to connect the anodes of D_4 and D_5 directly to V_{Bat} supply rail, thus eliminating the need for a device to block normal operating voltages   The line resistors, R_F, serve the dual purpose of being non-destructing energy dissipaters, when transients are clamped and of being fuses when the line is exposed to a power cross. Ericsson Components AB line resistor PBR 5067 is designed for this application.

Power-up sequence

The voltage at pin V_{Bat} sets the substrate voltage, which must at all times be kept more negative than the voltage at any other pin to prevent possible latch-up. The correct power-up sequence is ground and V_{Bat}, then other supplies and signal leads.

A diode with a 2A current rating connected with its cathode to V_{EE} and anode to V_{Bat} ensures the presence of the most-negative supply voltage at the V_{Bat} pin, if the V_{Bat} supply voltage should be absent. The V_{Bat} pin should not be applied at a faster rate than corresponds to the time constant formed by a 5.1ohm resistor in series with the V_{Bat} pin and a 0.47µF capacitor from the V_{Bat} pin to ground. This RC network may be shared by several SLICs.

Printed circuit board lay-out

Care in PCB lay-out is essential for proper PBL 3739 function. The components connecting to the RSN pin (30) should be in close proximity of that pin such that no interference is injected into the RSN terminal. Ground plane surrounding the RSN pin is advisable.

The switching regulator components must be located near the pins to which they connect. It is particularly important that the catch diode and the inductor be connected via the shortest possible trace lengths.

Ordering Information
Package	Temp. range	Part No.
CLCC	0 to +70°C	PBL 3739QC

ERICSSON ≥